



## Electrochemical deposition in an automatic system

Pure metal and alloy deposition as Au, Ag, Cu, Sn, Ni, SnAg for different applications in semiconductor and microsystem technologies. Enhanced liquid flow and electrical field control ensure a homogenous deposition at highest plating rates. RENA offers customised solutions for special applications.

### Areas of application

- Current redistribution layers for opto- and microelectronics
- Solder, Cu and Au bumps for wafer level packaging (WLP)
- Functional metallic layers for micro - electro - mechanical systems (MEMS)
- Micro forming and moulding for microsystems

### Features and benefits

- Modular design for maximum flexibility
- Edge exclusion < 3mm
- Convertible for 4", 6", 8", 12" or for special wafer geometries as rectangular substrates
- Additional process modules for pre-treatment, etching and drying available
- Customised solutions with various plating chemicals
- Single and stacked layer processes
- No cross contamination
- High quality
- > 15 years experience in plating tools

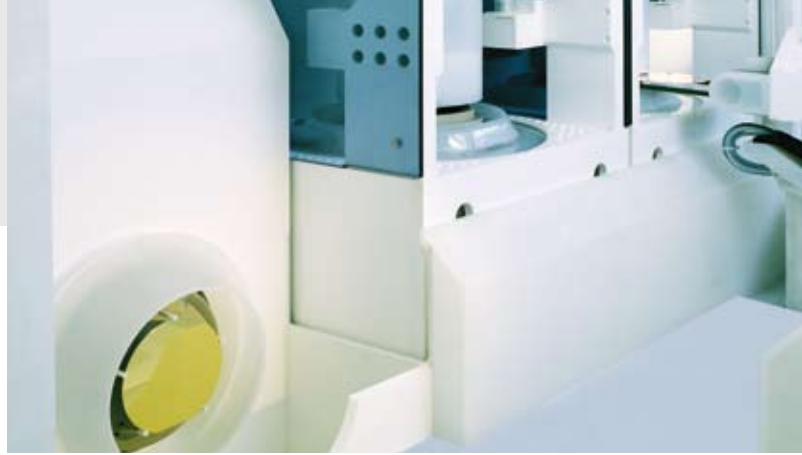




Fountain plater



Wafer loading



Modular design

## Technical Data EPA

**Process**

- Automatical loading
- Pre-treatment / rinsing
- Electroplating
- Rinsing/ etching
- Drying
- Automatical unloading

**Dimensions**

Depending on configuration

**Throughput**

Depending on configuration and process

**Wafer thickness**

> 400 µm

**Media consumption**

- DI water 200 l/h
- Electricity 380-400V / 50-60Hz
- Exhaust depending on configuration
- Compressed dry air for pneumatics